



Florida CirTech



PCFAB Products

1309 N. 17th Ave. Greeley, CO 80631 | www.floridacirtech.com

PCFAB Product Line

Final Finishes

SN100C[®] Lead Free Hot Air Level (HASL) Process

Nihon Superior Sn-Cu-Ni Lead free HASL with many OEM approvals.

Hot Air Fluxes & Oils

Vertical HASL fluxes: RAJ 65A and HA 305

Horizontal HASL fluxes: HA1040

Reflow oils: WS 220

Lead Free Solder: SN100 CL and CLE (replenishment) Sn-Cu-Ni-Ge based solder.

63/37 Solder: Nitro Flo high quality low dropping solder.

Electroless Nickel and Immersion Gold 300 Series Process

Two part system that is a stable pH self regulating chemistry.

Immersion Silver Finish

Superior Silver finish with optional anti-tarnish post dip.

Plating

Electroless Copper Systems

EC 200: Highly stable, low deposition bath that plates 1 micro inch per minute at 80°F.

EC 74: Medium deposition bath that plates 2-3 micro inches per minute at 80°F.

Direct Metallization

Omega II is a direct metallization process based on Palladium.

Brighteners

CP 157: One part Copper plating brightener.

SP 130: One part Tin brightener.



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Imaging

Sanwa Chemical Products

- Sanwa LC Series: LC Series is an excellent solder mask. Available in a variety of colors. Matte and Glossy.
- Sanwa S-22: LPI solder mask suitable for spray applications.
- UR 3100: UV curable solder mask.
- SM 530: Thermal curable lefend ink.
- UE-9000: UV curable etch resist.

Water Based Liquid Photoresist

- AQ 3000: Water based high resolution liquid photoresist.

Developers

- DV 200: Potassium Carbonate based developer.
- DV 205: High capacity Potassium Carbonate based developer system.

Photoresist Strippers

- RS 5000: VOC-free resist stripper suitable for inner-layer stripping.
- RS 5002: Low VOC-free resist stripper suitable for inner-layer stripping.
- RS 6040: A very fast resist stripper designed to strip inner layer.
- RS 7000: Economical outer layer resist stripper.

Lamination

Power Bond Oxide Replacement Process

- PB 445: Power Bond bath is an alternative to brown/black oxides. Power Bond is based on a Sulfuric/Peroxide microetch.

Other Chemicals

Tin/Solder Strippers

- EZ 5050: One part Nitric acid/Ferric Nitrate based solder stripper.
- EZ 7001: Concentrated replenisher for EZ 5050 conveyORIZED solder stripper.
- SSA & SSB: First part of our two part system.
- SS 2: Second part of our two part system.



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Micro-Etches

CirEtch 100: Powdered persulfate based micro-etch.
Superior topography and good stability.

CirEtch 130: Stabilized Hydrogen peroxide based micro-etch.

SS 3: Ferric chloride based copper cleaner with minimal etch rate.

Acid Cleaners

CB 709: Tri-acid based acid cleaner suitable as an inner layer core cleaner.

PC 5009: Acid blend soak cleaner prior to copper plate.

Screen Cleaners

SC 4: Environmentally friendly screen cleaner with orange oil for increased solvency.

SC 5: Glycol ether-ester blend. With excellent solvency.

LPI Solder Mask Strippers

RS 3150: Specially formulated for stripping fully cured LPI solder mask.

Equipment Cleaners

EC 2: Our most concentrated equipment cleaner for long life and re-usability.

Defoamers

BB 200: Non-silicone based defoamer.

BB 300: Defoamer used in developers and resist stripping.

Rinse Aids

RA 2000: Rinse Aid for a variety of processes to reduce ionic residues.

**Please visit www.floridacirtech.com
for more product information and technical details**

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